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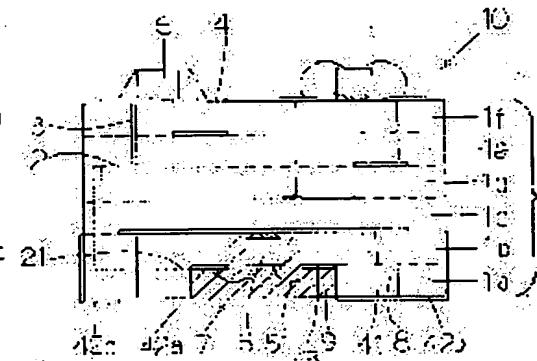
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(54) ELECTRONIC COMPONENT DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide an electronic component device which can reduce the size of the device, and enhance density and functions by increasing a mounted area of a base, and enhance the heat-dissipation performance of the device.

SOLUTION: In an electronic component device 10, the electronic component element 5 to be accommodates in a cavity 7 are disposed in an insulation base 1, which has the electronic component element accommodating cavity 7 and a terminal electrode 42 on the bottom, and a surface wiring conductor 4 and a circuit structure part 6 connected thereto are mounted to a surface of the insulation base 1. On a bottom surface of the cavity 7, there is provided a thermal via hole 8, which has a die attach conductive film 41 to which the electronic component element 5 is mounted, and extends in the thickness direction of the base 1, in the periphery of an opening of the cavity 7, for radiating heat generated by operation of the electronic component element 5 to the bottom surface side of the base 1. One end part of the thermal via hole 8 is jointed to the die attach conductive film 41, and the other end is exposed in the bottom surface of the base 1.



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